

HZM5.6ZFA

Silicon Epitaxial Planar Zener Diode for Surge Absorb

REJ03G1206-0300

(Previous: ADE-208-796B)

Rev.3.00

Jun 03, 2005

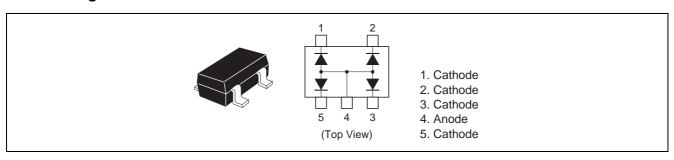
Features

- HZM5.6ZFA has four devices, and can absorb surge.
- Low capacitance (C = 8.5 pF max) and can protect ESD of signal line.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HM5.6ZFA	56Z	MPAK-5	PLSP0005ZC-A (MPAK-5)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol Value		Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	−55 to +150	°C

Note: Four device total, See Fig.2.

Electrical Characteristics *1

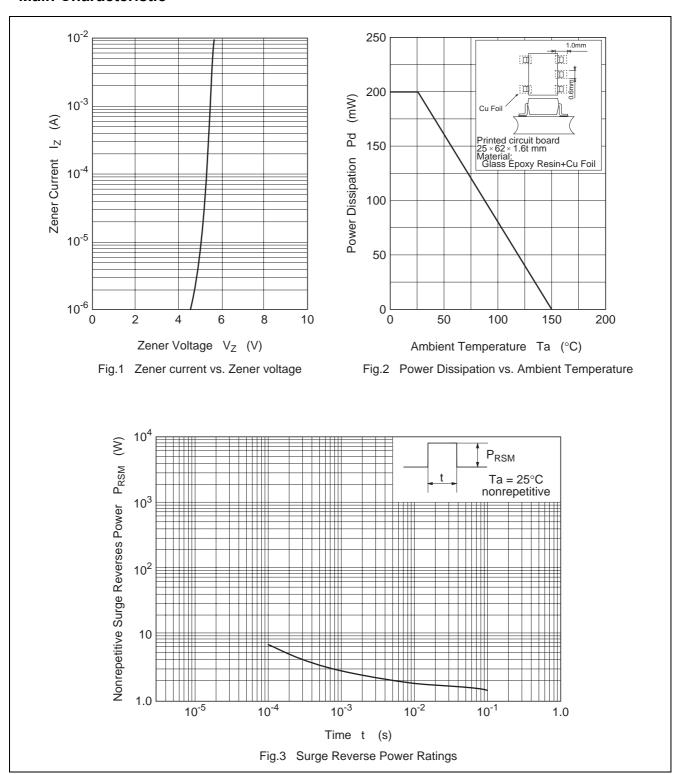
 $(Ta = 25^{\circ}C)$

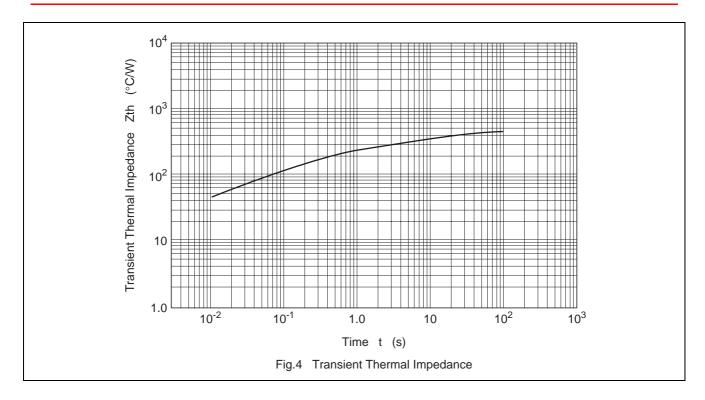
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	5.31	_	5.92	V	I_Z = 5 mA, 40 ms pulse
Reverse current	I _R	_	_	0.5	μΑ	V _R = 2.5 V
Capacitance	С	_	8.0	8.5	pF	V _R =0 V, f = 1 MHz
Dynamic resistance	r _d	_	_	80	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *2	_	8	_	_	kV	C = 150 pF, R = 330 Ω , Both forward and reverse direction 10 pulse.

Notes: 1. Per one device

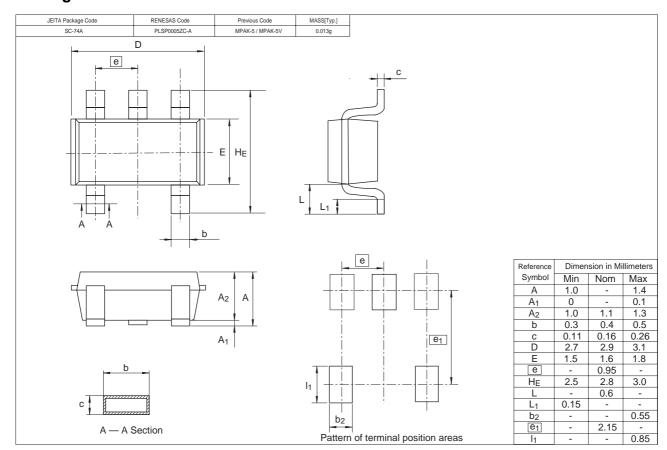
2. Failure criterion ; I_R > 0.5 μA at V_R = 2.5 V.

Main Characteristic





Package Dimensions



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